



Final Product Change Notification

202406016F01 : M9Z1x638 (Quibs.Z) Burn-in Elimination

Note: This notice is NXP Company Proprietary.

Issue Date: Jul 24, 2024 **Effective Date:** Oct 22, 2024

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Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input checked="" type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware <input type="checkbox"/> Other				

Notification Overview

Description

NXP Semiconductors announces the Burn-in elimination from the Final Test production flow for the M9Z1x638 (Quibs.Z) devices associated with this notification.

NXP Semiconductors works continuously on Burn-in time reduction and elimination on mature technologies like the M9Z1x638 SMOS8MV / SGF 0.18um, thanks to continuous process improvements to reduce latent defects.

The Burn-in elimination evaluation was successfully completed according to NXP specifications after testing 150k units corresponding to 164 wafers / 12 separate wafer lots of material, with zero Burn-in activated failures identified and without any impact on product quality. There are no historical customer quality incidents with corrective action requiring product Burn-in.

NXP respectfully requests customer's permission to implement Burn-in elimination production test flow immediately upon approval of PCN 202406016F01 to leverage the benefits of optimized processing.

Please see the attached files for additional details.

Corresponding ZVEI Delta Qualification Matrix ID: SEM-QG-01

Reason

Burn-in elimination for improved manufacturing capacity through optimized product cycle time and delivery.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Not Applicable

Samples not required for Burn-In elimination

Production

Planned first shipment Oct 17, 2024

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing data sheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification: view online

Additional documents: view online

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Aug 23, 2024.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name	Celine Dauptain
Position	Product Quality
e-mail address	celine.dauptain@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

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NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands

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12NC	Orderable Part Number	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	Product Line
935315214557	MM9Z1J638BM2EP	MM9Z1J638BM2EP	Precision Battery Sensor	H(V)QFN48PWF	SOT619-16	RFS	No	BLC3
935315214564	MM9Z1J638BM2EPR2	MM9Z1J638BM2EPR2	Precision Battery Sensor	H(V)QFN48PWF	SOT619-16	RFS	No	BLC3
935321951557	MM9Z1I638BM2EP	MM9Z1I638BM2EP	Precision Battery Sensor	H(V)QFN48PWF	SOT619-16	RFS	No	BLC3
935321951564	MM9Z1I638BM2EPR2	MM9Z1I638BM2EPR2	Precision Battery Sensor	H(V)QFN48PWF	SOT619-16	RFS	No	BLC3
935383126528	MM9Z1I638TM2EPR2	MM9Z1I638TM2EPR2	Precision Battery Sensor	H(V)QFN48WF	SOT619-25(D)	ASM	No	BLC3
935383126557	MM9Z1I638TM2EP	MM9Z1I638TM2EP	Precision Battery Sensor	H(V)QFN48WF	SOT619-25(D)	ASM	No	BLC3
935383128528	MM9Z1J638TM2EPR2	MM9Z1J638TM2EPR2	Precision Battery Sensor	H(V)QFN48WF	SOT619-25(D)	ASM	No	BLC3
935383128557	MM9Z1J638TM2EP	MM9Z1J638TM2EP	Precision Battery Sensor	H(V)QFN48WF	SOT619-25(D)	ASM	No	BLC3
935404277528	MM9Z1I638TM5EPR2	MM9Z1I638TM5EPR2	Precision Battery Sensor	H(V)QFN48WF	SOT619-25(D)	RFS	No	BLC3
935404277557	MM9Z1I638TM5EP	MM9Z1I638TM5EP	Precision Battery Sensor	H(V)QFN48WF	SOT619-25(D)	RFS	No	BLC3
935404279528	MM9Z1J638TM5EPR2	MM9Z1J638TM5EPR2	Precision Battery Sensor	H(V)QFN48WF	SOT619-25(D)	RFS	No	BLC3
935404279557	MM9Z1J638TM5EP	MM9Z1J638TM5EP	Precision Battery Sensor	H(V)QFN48WF	SOT619-25(D)	RFS	No	BLC3